# **DMA26403**

# Silicon PNP epitaxial planar type

For digital circuits

#### ■ Features

- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### ■ Basic Part Number

Dual DRA2144E (Individual)

#### Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

# ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-50	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V	
Collector current	$I_{C}$	-100	mA	
Total power dissipation	P <sub>T</sub>	300	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

### ■ Package

#### • Code

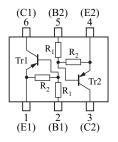
Mini6-G4-B

#### • Pin Name

1: Emitter (Tr1) 4: Emitter (Tr2) 2: Base (Tr1) 5: Base (Tr2) 3: Collector (Tr2) 6: Collector (Tr1)

## ■ Marking Symbol: H0

#### ■ Internal Connection



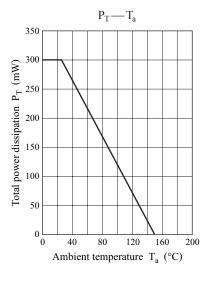
Resistance value	$R_1$	47	kΩ
	$R_2$	47	kΩ

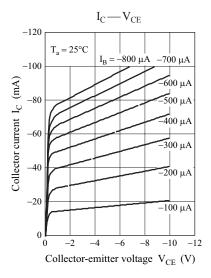
## ■ Electrical Characteristics $T_a = 25$ °C±3°C

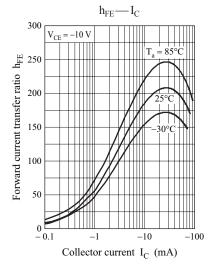
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = -10  \mu \text{A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{\rm CB} = -50 \text{ V}, I_{\rm E} = 0$			-0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = -50 \text{ V}, I_{B} = 0$			-0.5	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			-0.1	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	80			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA}$			-0.25	V
Input voltage (ON)	V <sub>I(on)</sub>	$V_{CE} = -0.2 \text{ V}, I_{C} = -5 \text{ mA}$	-3.6			V
Input voltage (OFF)	V <sub>I(off)</sub>	$V_{CE} = -5 \text{ V}, I_{C} = -100 \mu\text{A}$			-0.8	V
Input resistance	$R_1$		-30%	47	+30%	kΩ
Resistance ratio	$R_1/R_2$		0.8	1.0	1.2	_

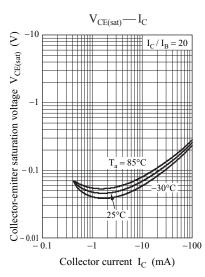
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

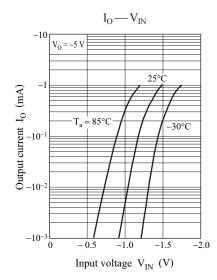
DMA26403 Panasonic

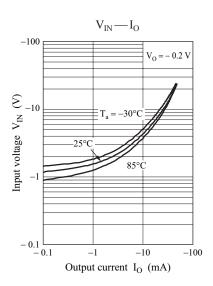






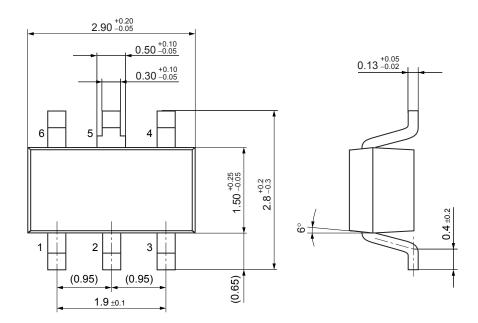


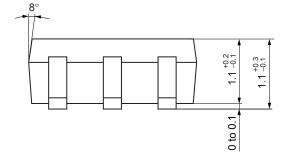




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Mini6-G4-B Unit: mm





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